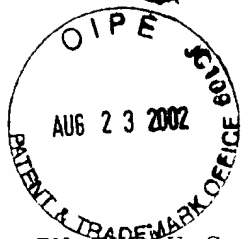


COPY OF PAPERS
ORIGINALLY FILED

PATENT
2565-0225P

\$17/C
DETAILS
7.9.3.02



IN THE U.S. PATENT AND TRADEMARK OFFICE

RECEIVED
SEP -3 2002
TECHNOLOGY CENTER 2800

Applicant: Shusou WADAKA et al. Conf.: 9099
Appl. No.: 09/778,872 Group: 2834
Filed: February 8, 2001 Examiner: Mark O. BUDD
For: FILM ACOUSTIC WAVE DEVICE AND ITS
MANUFACTURING METHOD AND CIRCUIT DEVICE

AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

August 23, 2002

Sir:

The following amendments and remarks are respectfully submitted in response to the Office Action dated May 28, 2002, in connection with the above-identified application.

IN THE CLAIMS:

Please amend the claims as follows:

24. (Once Amended) A wafer having a plurality of acoustic wave devices formed thereon and exhibiting common operational characteristics, each of said acoustical wave devices manufactured according to a method comprising:

(a) forming a ground electrode on the wafer which is intended to be placed on top of a semiconductor substrate;